

500 Main Street, Suite 18 PO Box 989 Deep River, CT 06417 USA

Toll Free: 800.435.0317 Phone: 860.526.8300 Fax: 860.526.8243 www.amtechsolder.com

NWS-4400-HA-LF, Water Washable Solder Paste

Product Data Sheet

Product Highlights

- REM1 flux classification
- Long stencil life and wide process window
- Anti-tombstoning
- No beading
- Low voiding
- Excellent wetting of oxidized finishes
- Compatible with enclosed print heads
- RoHS II and REACH compliant
- Print & Dispense grade solder paste available

Available Alloys

Alloy	Temp °C	Temp °F
42Sn/58Bi	138	280
42Sn/57Bi/1Ag	138	280
96.5Sn/3.0Ag/0.5Cu	217-220	423-428
99.0Sn/0.3Ag/0.7Cu	217-221	423-430
96.5Sn/3.5Ag	221	430
99.3Sn/0.7Cu	227	441
95Sn/5Sb	235-240	455-464
95Sn/5Ag	221-245	430-473

Packaging

500 gram jars 500 gram cartridges 35 or 100 gram syringes ProFlow cassettes

Test Results			
Test J-STD-004 or other requirements (as stated)	Test Requirement	Result	
Copper Mirror	IPC-TM-650: 2.3.32	M: <50% breakthrough	
Corrosion	IPC-TM-650: 2.6.15	M: Minor	
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%	
Electrochemical Migration	IPC-TM-650: 2.6.14.1	M: <1 decade drop (cleaned)	
Surface Insulation Resistance 85 °C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	M: ≥100 MΩ (cleaned)	
Tack Value	IPC-TM-650: 2.4.44	34g	
Viscosity - Malcom @ 10 RPM/25 °C (x10³mPa/s)- SAC305 T3/T4	IPC-TM-650: 2.4.34.4	Print: 210-270 Dispensing: 90-125	
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation	
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant	
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder material	

NWS-4400-HA-LF, Water Washable Solder Paste

Printer Operation

The following are general guidelines for stencil printer optimization with NWS-4400-HA-LF. Some adjustments may be necessary based on your process requirements.

Print Speed: 25-100 mm/sec Squeegee Pressure: 70-250g/cm of blade Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

> 8 hours @ 30-45% RH and 20-25 °C ~ 4 hours @ 45-75% RH and 20-25 °C

Cleaning

NWS-4400-HA-LF can be cleaned using deionized water at 40-60 °C with a recommended water pressure of 30-50 PSI. NWS-4400-HA-LF can also be cleaned using commercially available flux residue removers such as Kyzen Aquanox A4241, A4520, A4625 and A4625B (Batch Cleaners). Kyzen brand cleaners are available from Amtech.

Amtech Low Oxide Powder Distribution

Micron Size	Туре	Pitch Requirements
45-75μ	Type-2	24 mil and above
25-45µ	Type-3	16-24 mil
20-38µ	Type-4	12-16 mil
15-25µ	Type-5	8-12 mil
5-15µ	Туре-б	5-8 mil
2-11µ	Type-7	< 5 mil

Note: Type-6 and Type-7 may not be available in certain alloys. Other powder distributions are available on request.

Storage

Solder paste should be stored between 3-8 °C (37-46 °F) to obtain the maximum refrigerated shelf life of six months. Unopened solder paste stored at room temperature, 25 °C (77 °F) will have a one month shelf life. Syringes and cartridges should be stored vertically in the refrigerator with the dispensing tip down. Allow 4-8 hours for solder paste to reach an operating temperature of 20-25 °C (68-77 °F). Keep the solder paste container sealed while warming the solder paste to operating temperature.

NEVER FREEZE SOLDER PASTE.

Profile for Sn96.5/Ag3.0/Cu.5 and Sn96.5/Ag3.5 alloys 300 starting point for process optimization Peak Temperature (Min 230°C-Max 249°C) 250 Liquidus Temperature 219 200 Reflow Time: Flux Activation Temperature (0°) 30-60 Sec. 150 RAMP @ < 2.0°C/Second Temp. Soaking Zone 100 Soak Temp 140-200°C 50 Soak Time 60-90 Sec Pre-heat 1 Pre-heat 2 Reflow Zone Cooling 0 30 60 90 120 150 180 210 240 270 300 330 Time (Sec.)

AMTECH Part Numbers

<60 seconds.

Recommended Profile

This profile is designed to serve as a

using NWS-4400-HA-LF. To achieve

reduce tombstoning, consider using

a longer soaking zone, (170-220 °C)

pre-heat stage. If there is evidence of

solder de-wetting, consider lowering

better results with voiding or to

for 60-90 seconds, with a rapid

the peak reflow temperature, or

reduce the time above liquidus to

NWS-4400-HA-LF 96.5Sn/3.0Ag/0.5Cu, Type 3, 500 gram jar: Part Number: 11760 NWS-4400-HA-LF 96.5Sn/3.0Ag/0.5Cu, Type 4, 500 gram jar: Part Number: 11755 NWS-4400-HA-LF 96.5Sn/3.0Ag/0.5Cu, Type 3, 500 gram cartridge: Part Number: 11750 NWS-4400-HA-LF 96.5Sn/3.0Ag/0.5Cu, Type 4, 500 gram cartridge: Part Number: 11751 Other alloy and packaging combinations available upon request.